

ABSTRACT OF THE DISCLOSURE

A processing equipment is provided with a vessel having one gas discharge port or more 12a to 15a, a substrate holder 4 provided in the vessel, and a rotating body 2 provided between the substrate holder 4 and a side wall 1 of the vessel to rotate around the substrate holder 4 and having one vent hole or notched vent portion or more, wherein a gas is discharged onto the substrate holder 4 from the gas discharge port 12a to 15a when the gas discharge port 12a to 15a coincides in position with the vent hole 16, or the like of the rotating body 2 by rotating the rotating body 2. Accordingly, there can be provided a processing equipment and a processing method capable of achieving reduction in time required for one cycle applied to laminate one atomic layer, making a computer control possible, facilitating maintenances including fitting and removal of parts of the equipment, and facilitating disassembly and cleaning of the equipment.